

AMENDMENTS TO THE SPECIFICATION

Please amend Paragraphs [0021]-[0022] as indicated below.

[0021] In an embodiment, water in the heat pipe 101 is heated, causing the water to change into steam and rise. This rising hot water vapor brings heat to the heat sink 103. In an embodiment, a heat pipe 101 includes a metal weave interior to accelerate the heat transfer. Heat from the heat sink 103 is transferred to the air surrounding it, and this hot air is blown out of a computer chassis by a fan. As the water vapor in the heat pipe 101 near the heat sink 103 condenses into water, losing heat energy, the water vapor flows back into the heat pipe 101 and is available [[for]] to be heated again. In this process, heat generated by the CPU is removed from the housing of the personal computer.

[0022] The number of heat ~~pipe~~ pipes 101 is selected according to the heat dissipation requirements of the system. Generally speaking, a heat pipe ~~2+~~ 101 in accordance with an embodiment of the present invention can absorb heat at a rate of about 30 to 40 Watts. High performance processors alone can generate up to 100 Watts, thus making it preferable to use at least three to four heat pipes.